

Application No.: 10/055,560

Docket No.: JCLA8532

REMARKS

This is a full and timely response to the outstanding nonfinal Office Action mailed Jan. 27, 2005. Reconsideration and allowance of the application and presently pending claims are respectfully requested.

1. Present Status of the Application

Upon entry of the amendments in this response, claims 139-241 remain pending in the present application. More specifically, claims 139-241 are newly added; and claims 1-138 are canceled without prejudice, waiver, or disclaimer. These additions are specifically described above. It is believed that the foregoing additions add no new matter to the present application.

2. Response To Objections/Rejections

Applicants respectfully traverse the rejections for at least the reasons set forth below.

Response To Claim 139-194

As originally recited, independent claim 139 and 170 recites below:

139. A chip packaging method comprising:
joining at least a die and a substrate;
after said joining said at least a die and said substrate, depositing at least a passive device over said substrate; and
separating said substrate.

170. A chip packaging method comprising:
joining at least a die and a substrate;
after said joining said at least a die and said substrate, depositing at least a passive device and at least a trace over said substrate; and
separating said substrate.

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Applicants teach the concept that after at least a die and a substrate are joined, at least a passive device is deposited over a substrate, which is not taught by Mu et al., Towle et al. and Tahara et al.

For at least the foregoing reasons, Applicant respectfully submits that independent claims 139 and 170 patentably define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 140-169, and 171-194 patentably define over the prior art as well.

Response To Claim 195-222

As originally recited, independent claim 195 recites below:

195. A chip packaging method comprising:
joining at least a die and a substrate, said die having a top surface at a horizontal level;
after said joining said at least a die and said substrate, depositing at least a passive device over said horizontal level; and
separating said substrate.

Applicants teach the concept that after at least a die and a substrate are joined, at least a passive device is deposited over a horizontal level at which a top surface of the joined die is positioned, which is not taught by Mu et al., Towle et al. and Tahara et al.

For at least the foregoing reasons, Applicant respectfully submits that independent claim 195 patentably define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 196-222 patentably define over the prior art as well.

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As originally recited, independent claim 223 recites below:

223: A chip packaging method comprising:
providing at least a die having a top surface at a horizontal level; and
depositing at least a passive device over said horizontal level, wherein *there is no die under said at least a passive device.*

Applicants teach the concept that at least a passive device is deposited over a horizontal level at which a top surface of a die is positioned, wherein there is no die under the deposited passive device, which is not taught by Mu et al., Towle et al. and Tahara et al.

For at least the foregoing reasons, Applicant respectfully submits that independent claim 223 patentably define over the prior art references, and should be allowed. For at least the same reasons, dependent claims 224-241 patentably define over the prior art as well.

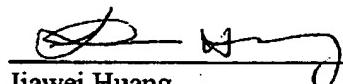
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For at least the foregoing reasons, it is believed that the pending claims 139-241 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
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